



THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of:

VICTOR TAN CHER 'KHNG  
LEE KIAN CHAI

Serial No. 10/023,049

Art Unit: 2822

Filing Date: 12/20/2001

Examiner: Graybill, David E.

For: Semiconductor Package Having  
Substrate With Multi-Layer  
Metal Bumps

Attorney Docket No. 00-1117

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**AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED  
EXAMINATION (RCE) UNDER 37 CFR 1.114**

**July 19, 2006**

Mail Stop RCE  
Commissioner For Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

This Amendment is in response to the Office Action dated 05/15/2006, having a statutory period for response set to expire on 08/15/2006. Please amend the application as follows.